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RELEASED FOR PUBLICATION

20

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BY -

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LOC

DIST

REVISIONS

P

LTR

DESCRIPTION

DATE

DWN

APVD

2

REVISED

30AUG2017

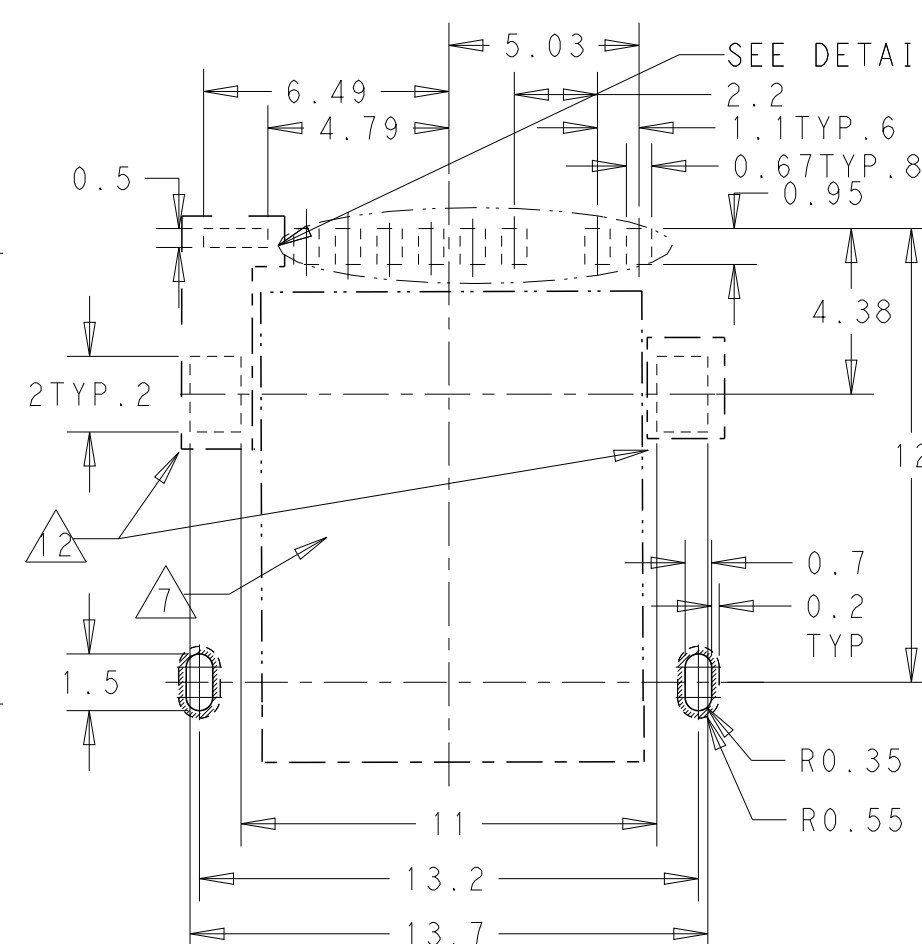
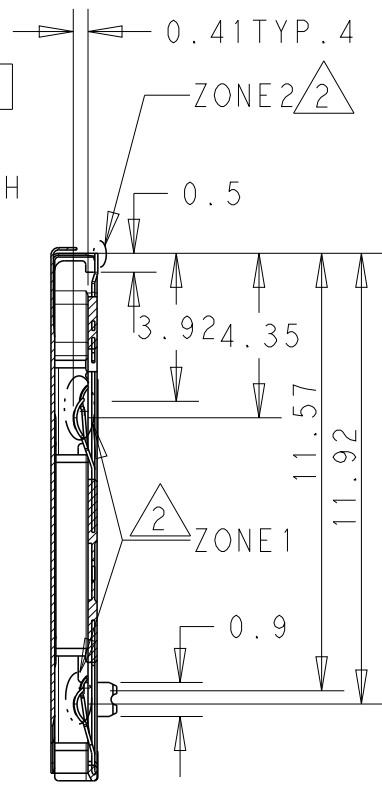
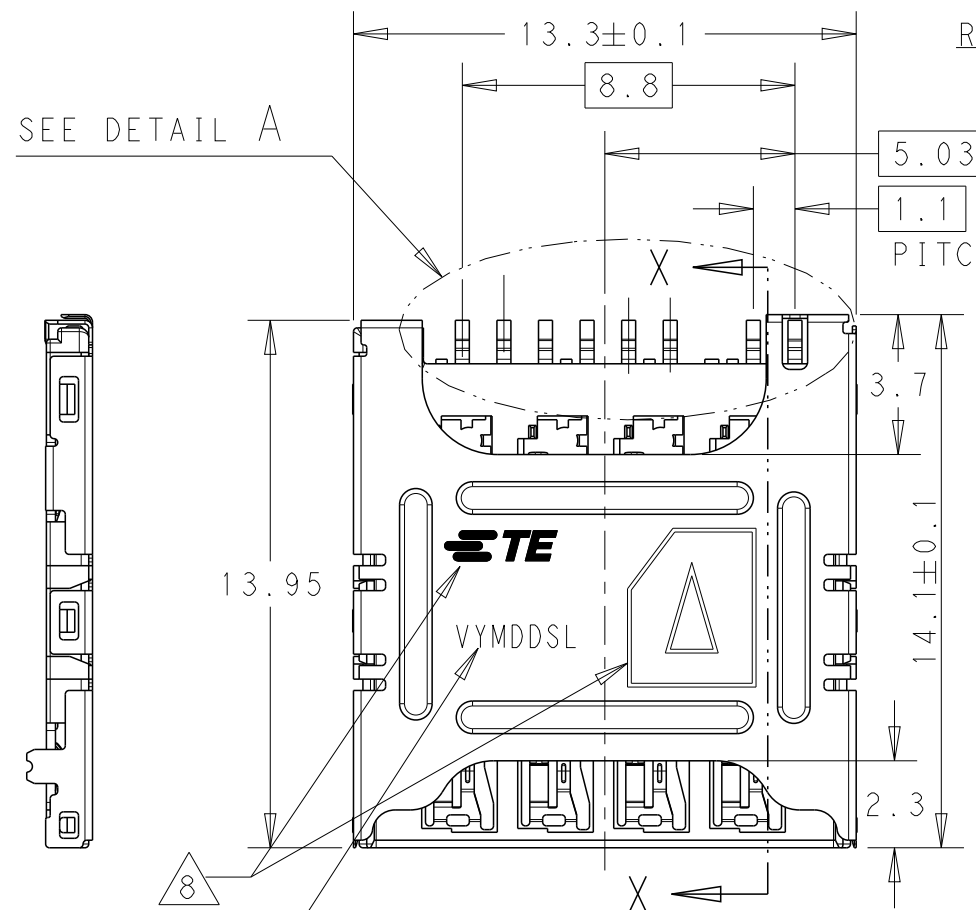
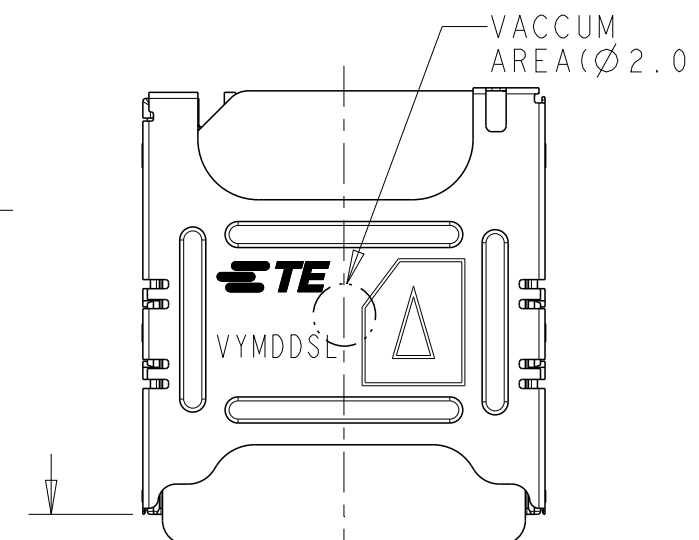
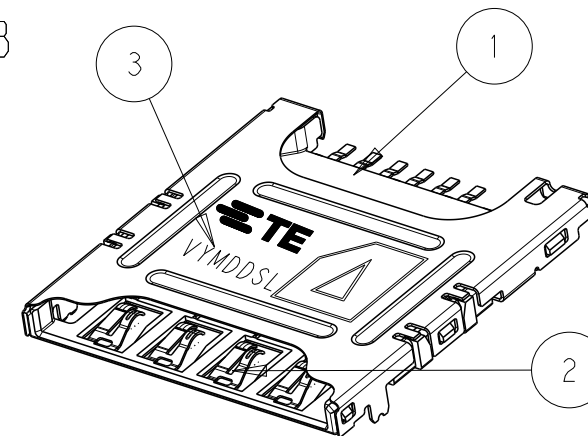
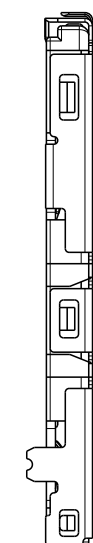
R.Z

S.L

RESTRICTED TO SAMSUNG ELECTRONICS

SEE DETAIL A

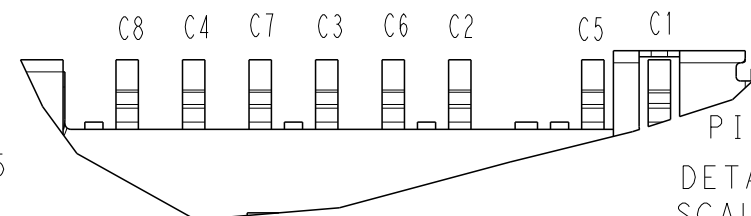
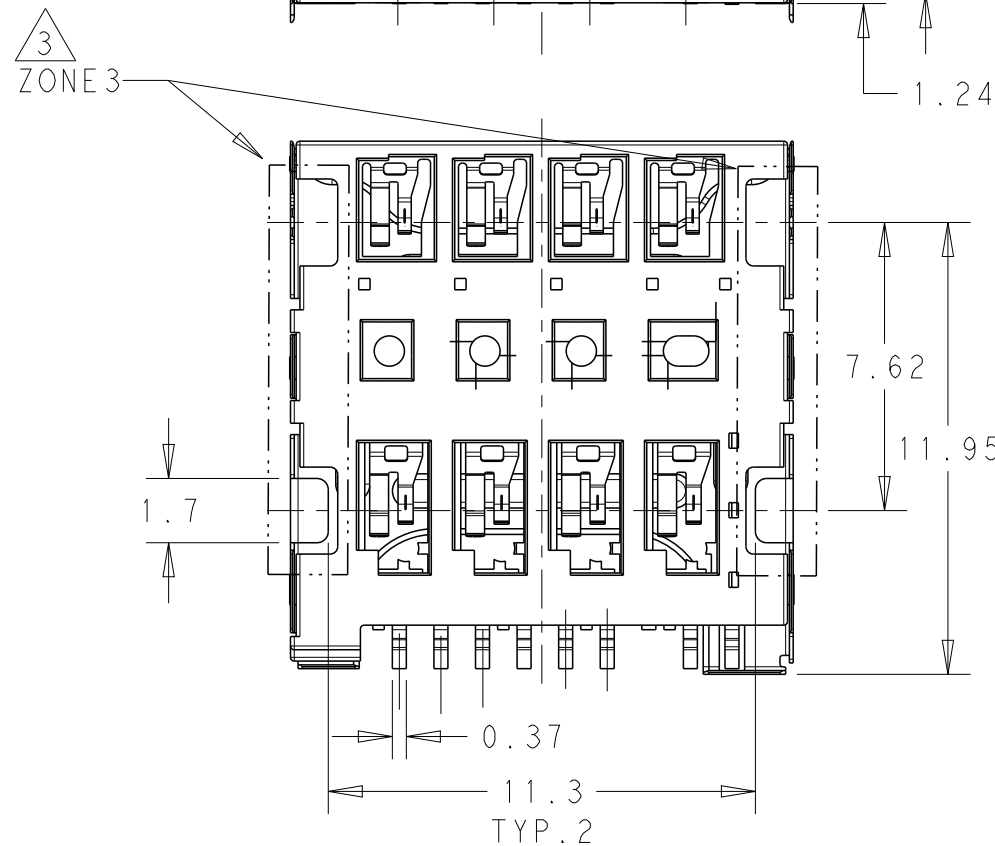
SEE DETAIL B



SCALE 5:1

<8POS PCB LAYOUT>
TOLERANCE: ±0.05

1 REF
<MATING CONDITION>



DETAIL A
SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN WJ.CHOI 14MAR2013

CHK WJ.CHOI 14MAR2013

APVD JH.KIM 14MAR2013

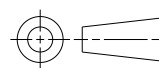
PRODUCT SPEC

APPLICATION SPEC

WEIGHT -

CUSTOMER DRAWING

DIMENSIONS:
mm



TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC ±0.2
1 PLC ±0.2
2 PLC ±0.2
3 PLC ±0.2
4 PLC ±0.2
ANGLES ±2

MATERIAL



SEE TABLE

FINISH

NAME

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO



TE Connectivity

MICRO SIM H1.24
Push-Pull DIP 0.3 TYPE
(ONLY USAGE FOR FPCB)

A3

00779

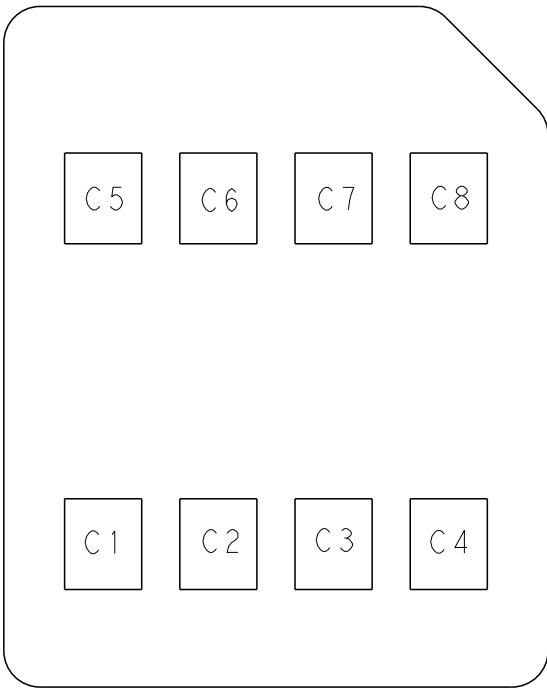
C-2108556

SCALE 5:1

SHEET 1 OF 3

REV 2

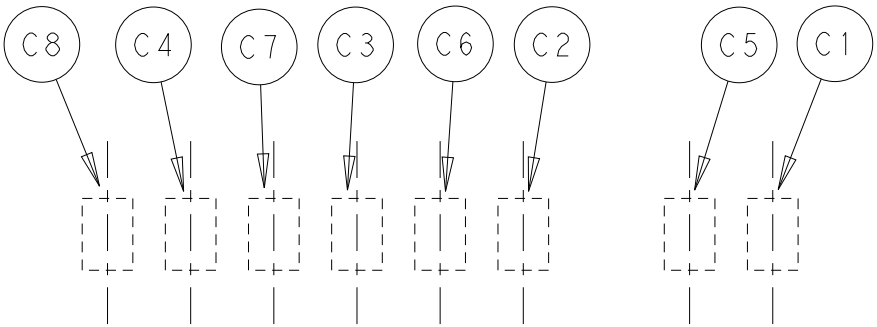
0.76±0.08



SIM CARD PAD LAYOUT

C8	RESERVED
C7	I/O
C6	VPP
C5	GND
C4	RESERVED
C3	CLK
C2	RST
C1	VCC
PIN No.	PIN NAME

SIM CARD PIN ASSIGNMENT



PCB LAYOUT(REFERENCE)
(VIEW FROM CONNECTOR MOUNT SIDE)

DETAIL B
SCALE 10:1

DESIGN APPROVED THIS PRINT IS

PRELIMINARY

TO FIRST PIECE APPROVAL
CONTACT PRODUCT ENGINEERING
BEFORE USING THIS PRINT

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN WJ.CHOI	14MAR2013	TE Connectivity				
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	CHK WJ.CHOI	14MAR2013					
		APVD JH.KIM	14MAR2013					
	0 PLC ±0.2 1 PLC ±0.2 2 PLC ±0.2 3 PLC ±0.2 4 PLC ±0.2 ANGLES ±2	PRODUCT SPEC		NAME MICRO SIM H1.24 Push-Pull DIP 0.3 TYPE (ONLY USAGE FOR FPCB)				
		-						
		APPLICATION SPEC						
MATERIAL -	FINISH SEE TABLE	-		SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO -	
		WEIGHT -		A3	00779	C-2108556		
		CUSTOMER DRAWING		SCALE 5:1				
				SHEET 2			OF 3	REV 2

4

3

2

1

